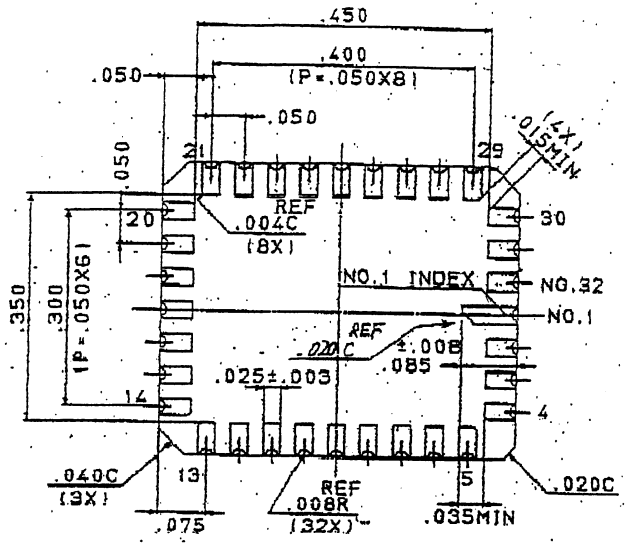
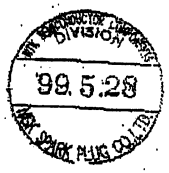
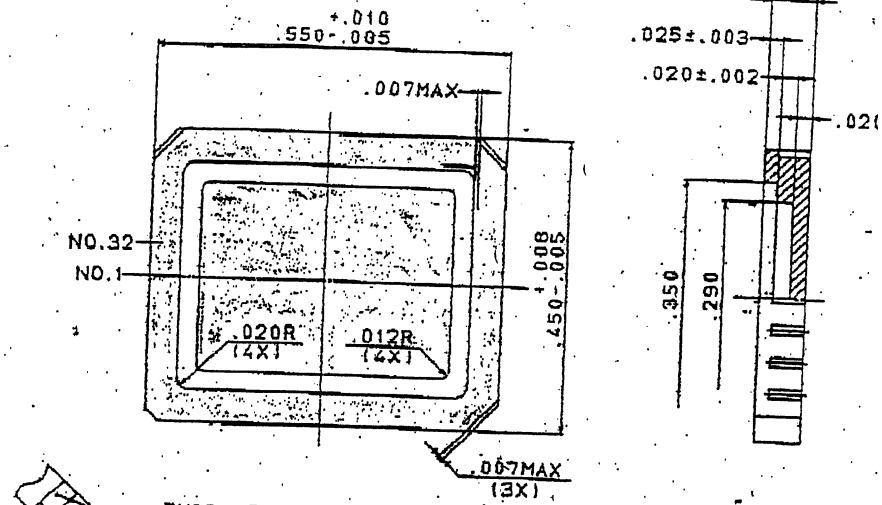
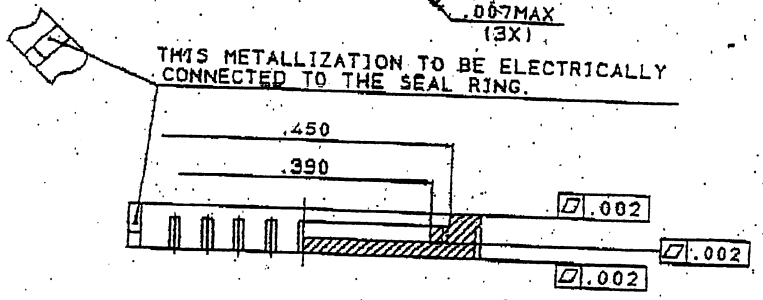






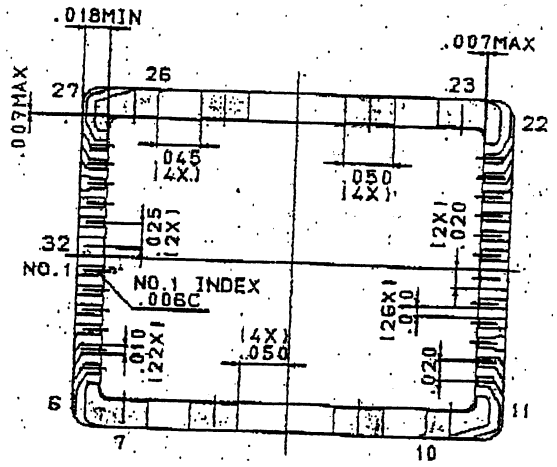


NOTES: 1. GOLD PLATE 60 μ INCHES MIN OVER 100 μ INCHES MIN. NICKEL.

2. NO LEAD TO BE ELECTRICALLY CONNECTED TO DIE ATTACH PAD, SEAL RING ISOLATED.

SSM P/N

LCC03236



B/G PAD DETAIL

SSM P/N

LCC03236

CERAMIC	BLACK ALUMINA		#	NEW DRAWING	JAN-25 -1989
Item Name	Material	Description	Rev.	Description	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 2 DECIMALS .XX ±.01 3 DECIMALS .XXX ±.005		DRAWN S.Matsuzawa	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD		
		CHECKED T. Hai			
CUSTOMER		APPROVED O. Tokoro	TITLE 32 LEAD CHIP CARRIER		
DWG NO.		UNIT INCH			
		SCALE			

IRK32F1-5251B